

FIG .1

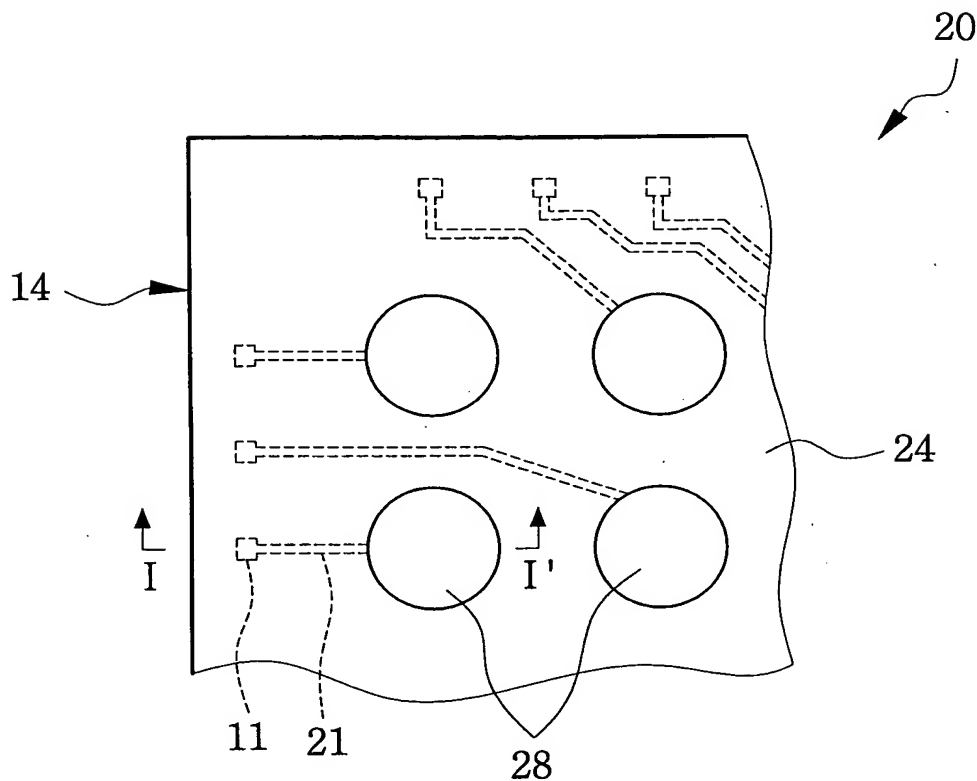
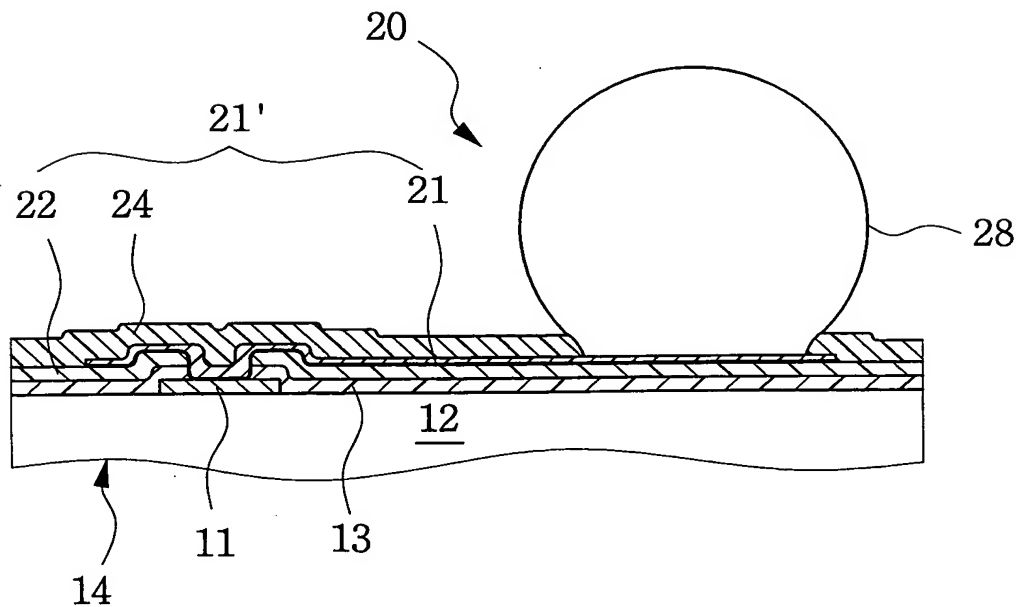


FIG .2



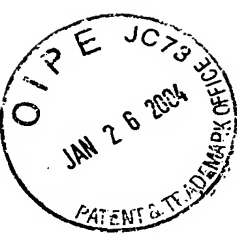


FIG .3

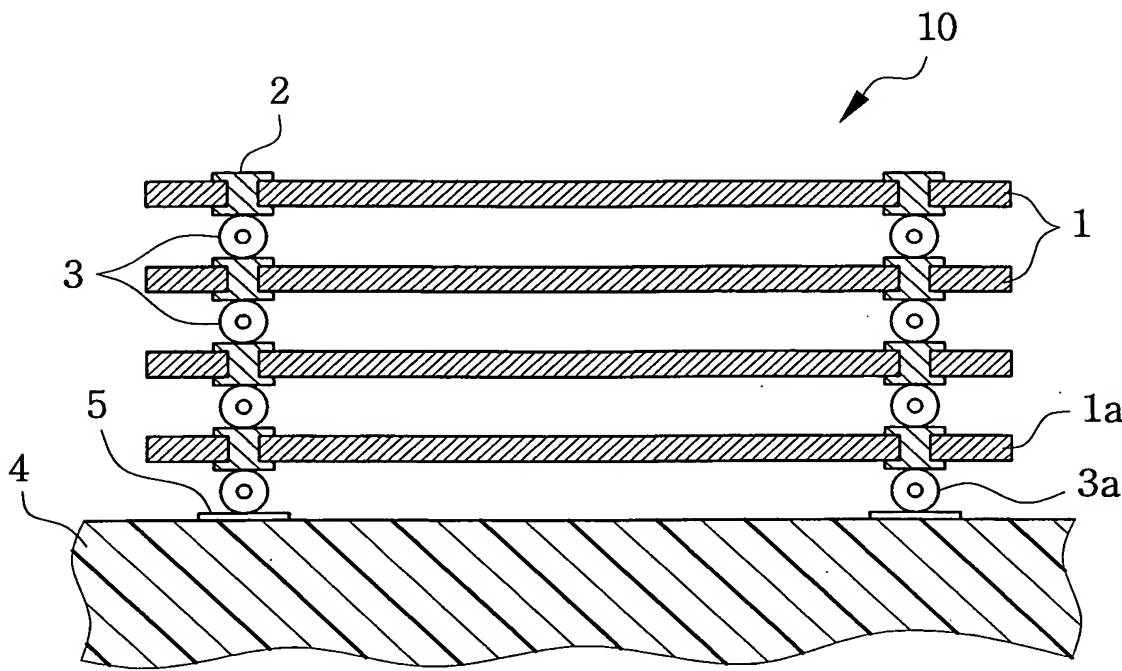
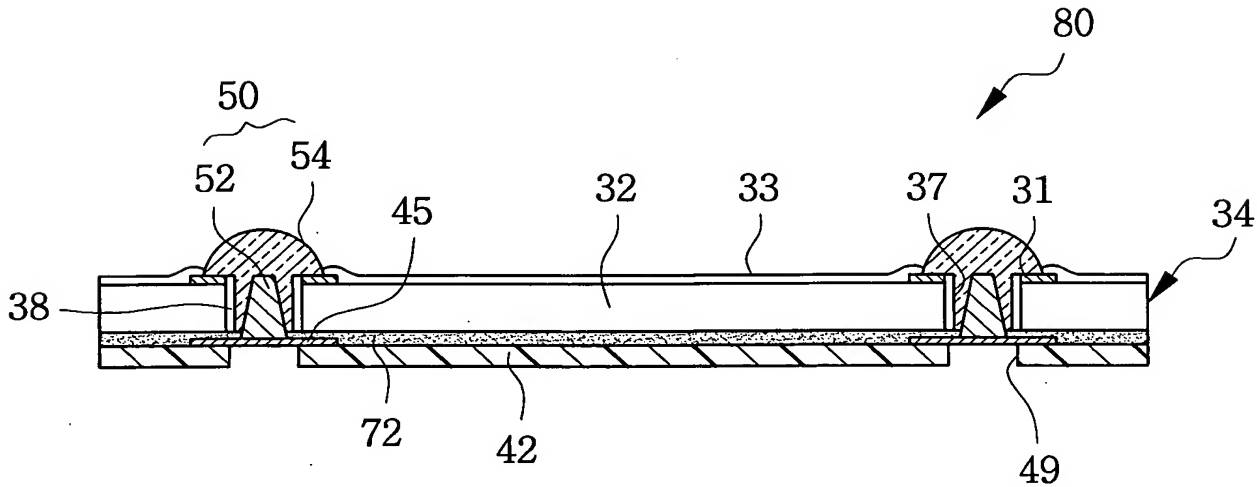


FIG .4





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FIG .5

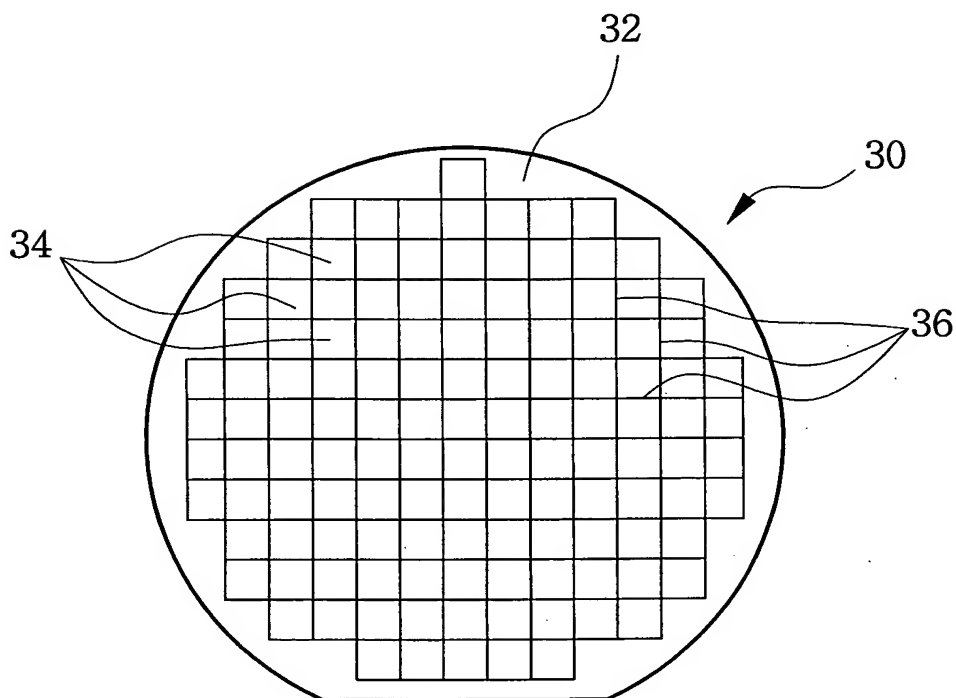
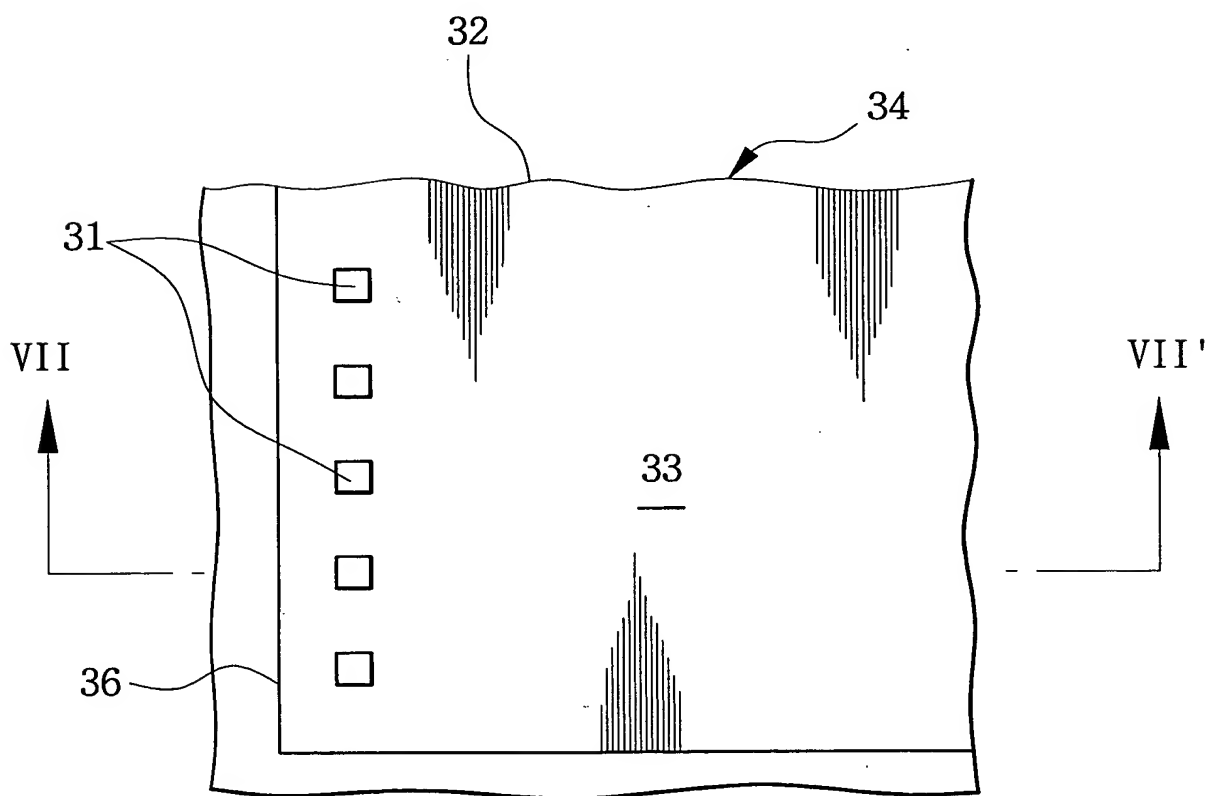
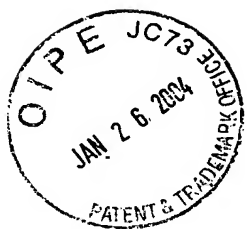


FIG .6





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FIG .7

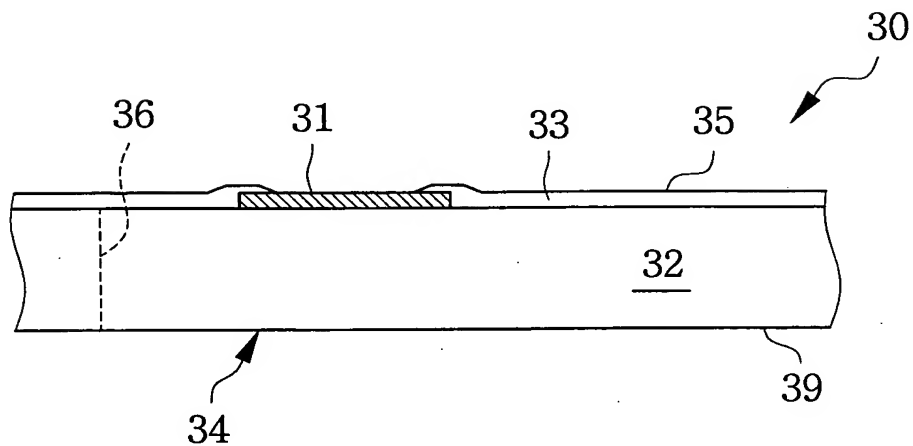
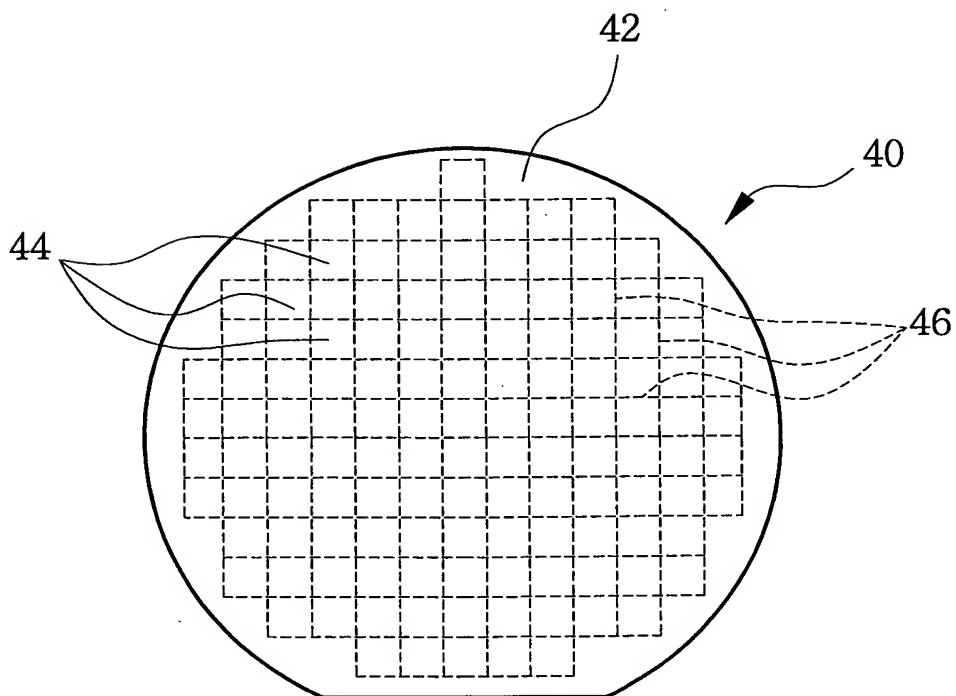


FIG .8



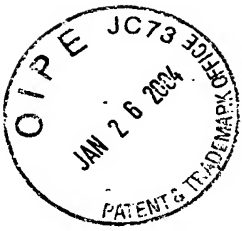


FIG .9

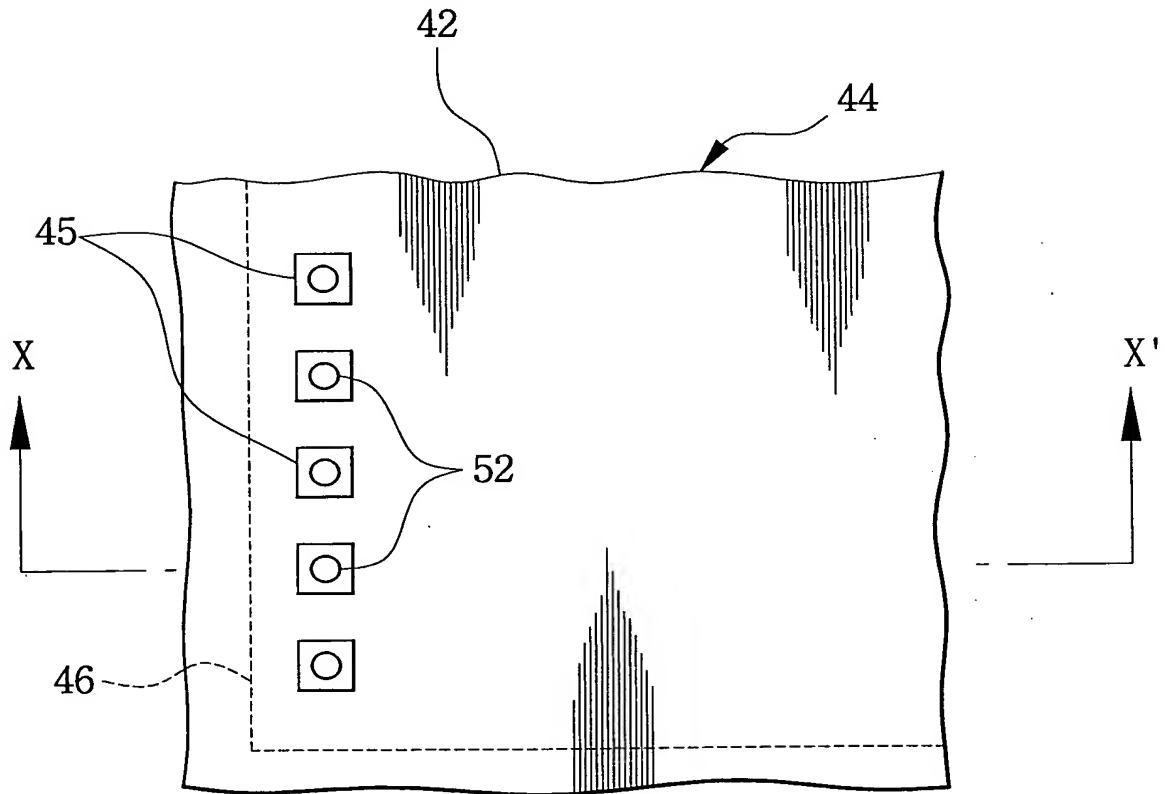
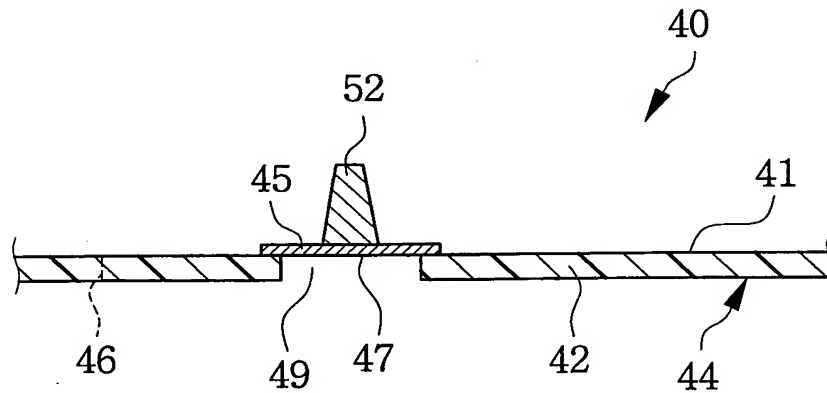
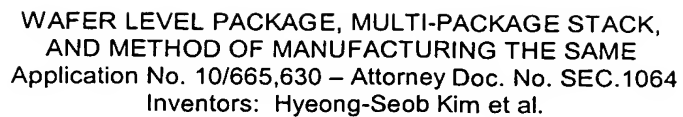


FIG .10



[illegible]

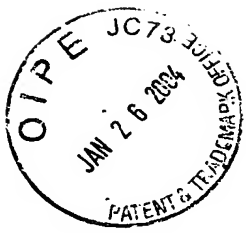


FIG .12b

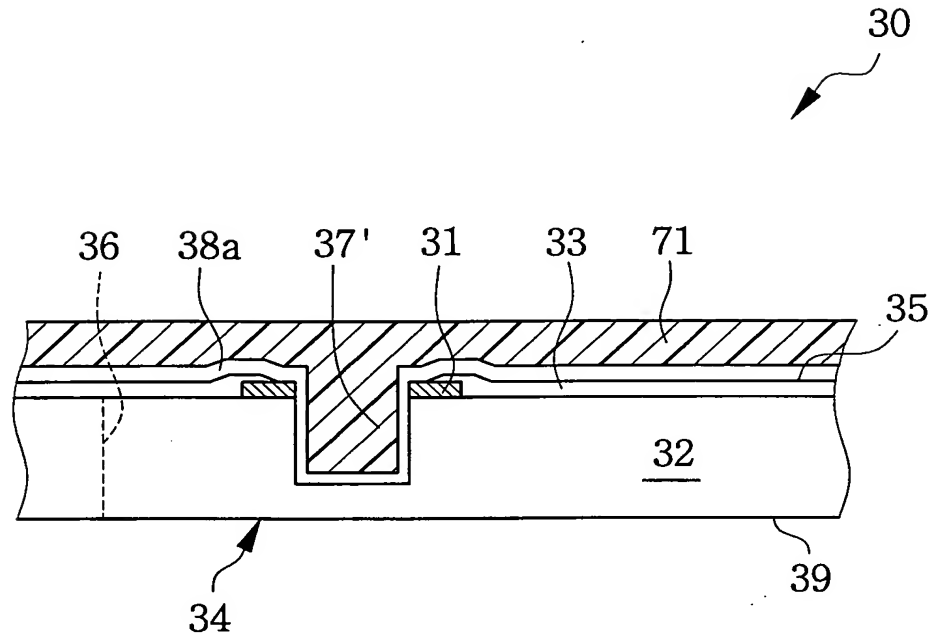
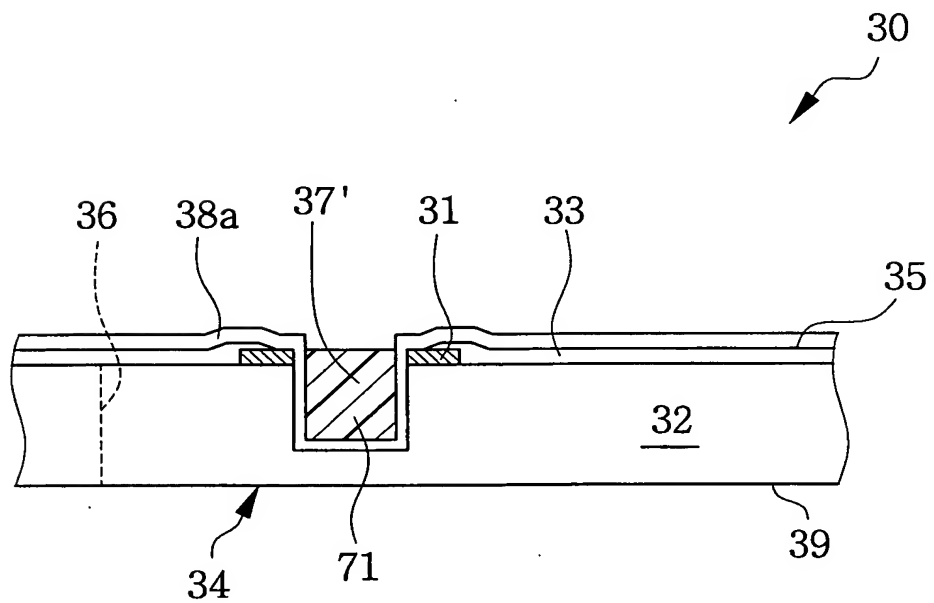


FIG .12c



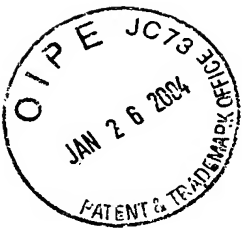


FIG .12d

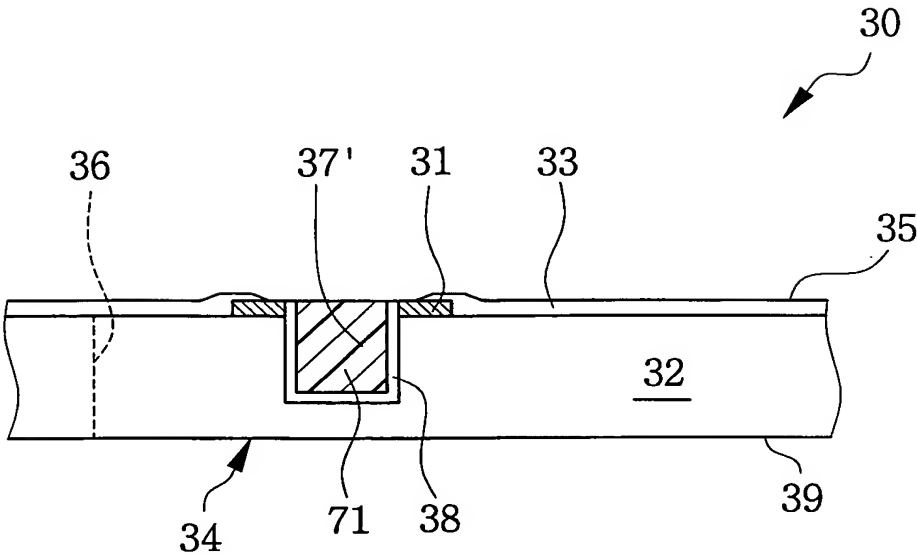
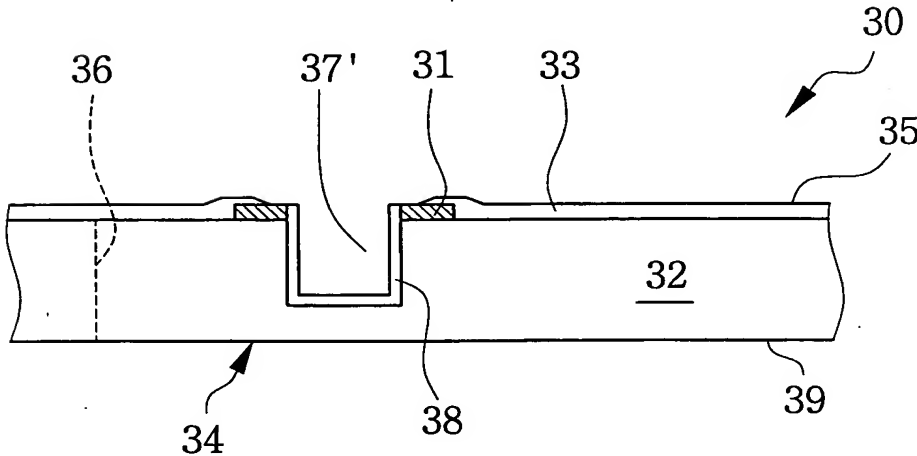
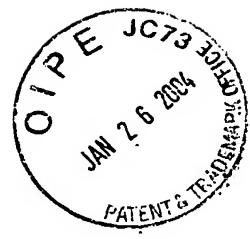


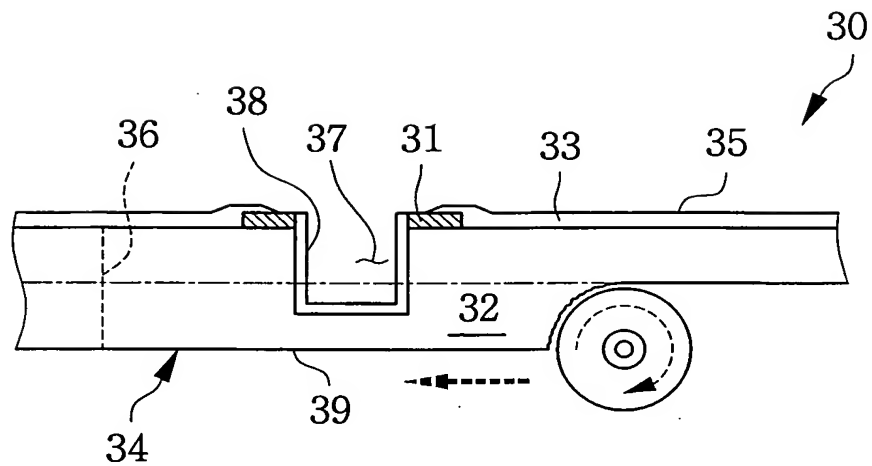
FIG .12e





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FIG .13



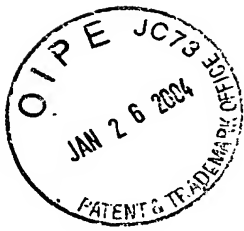


FIG .16

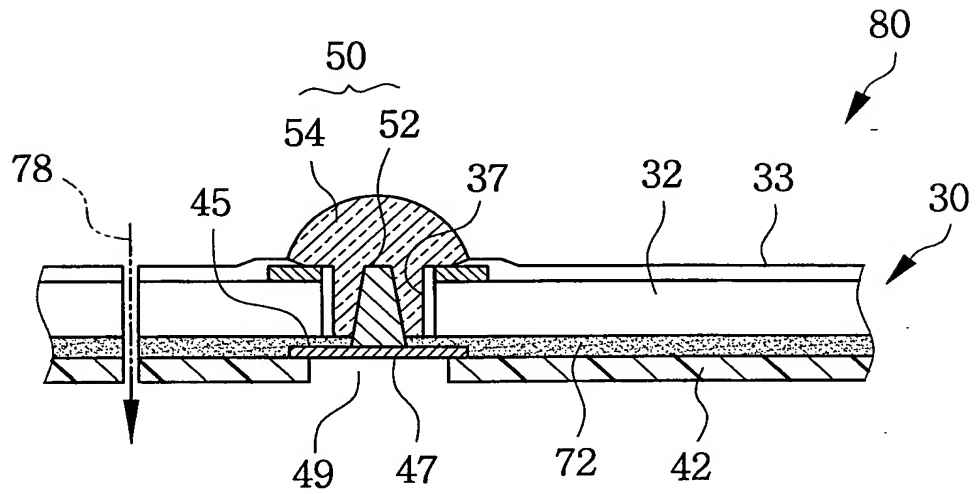
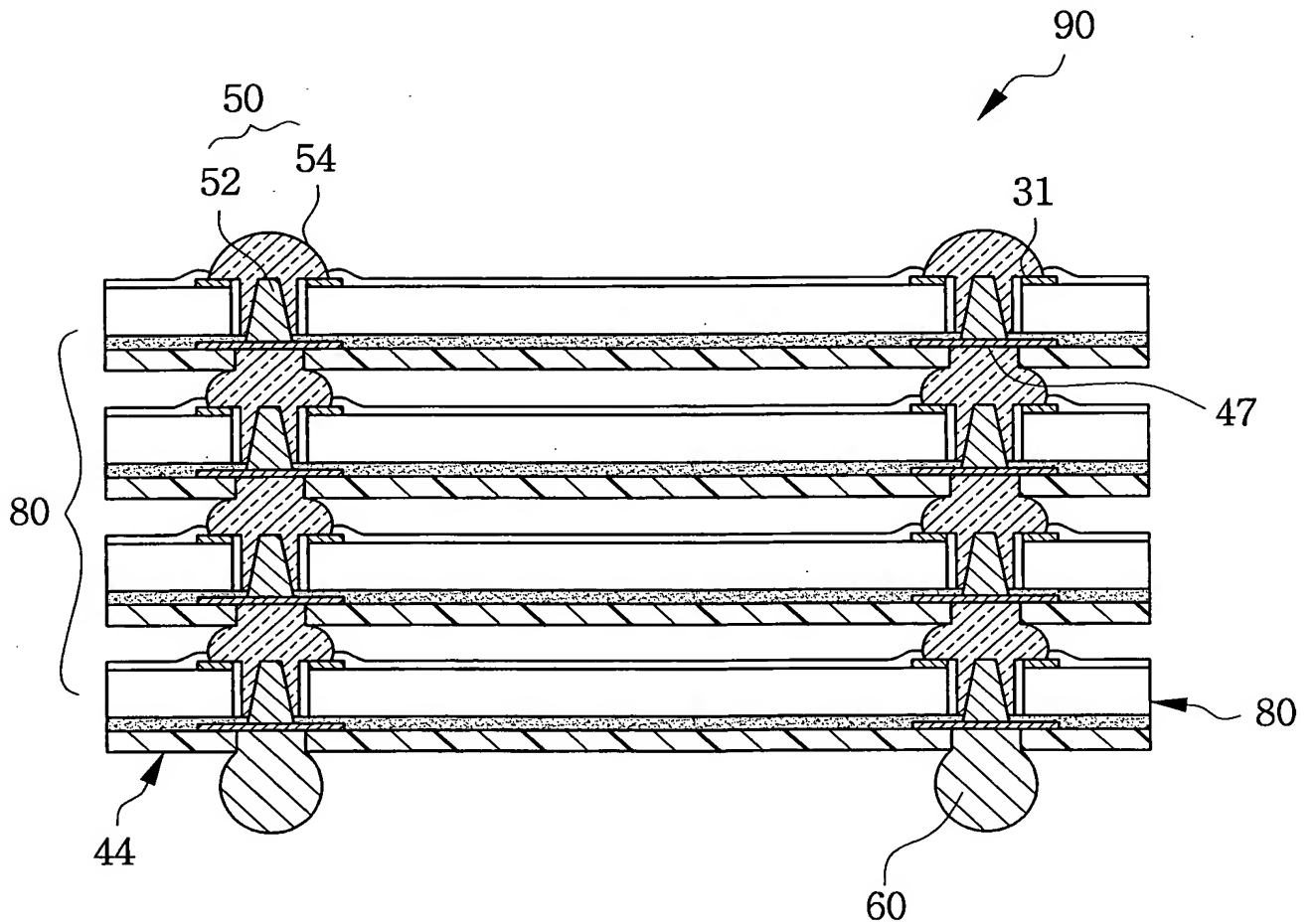
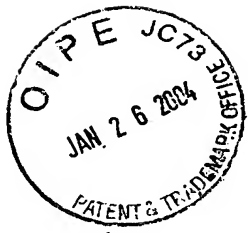


FIG .17





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FIG .18

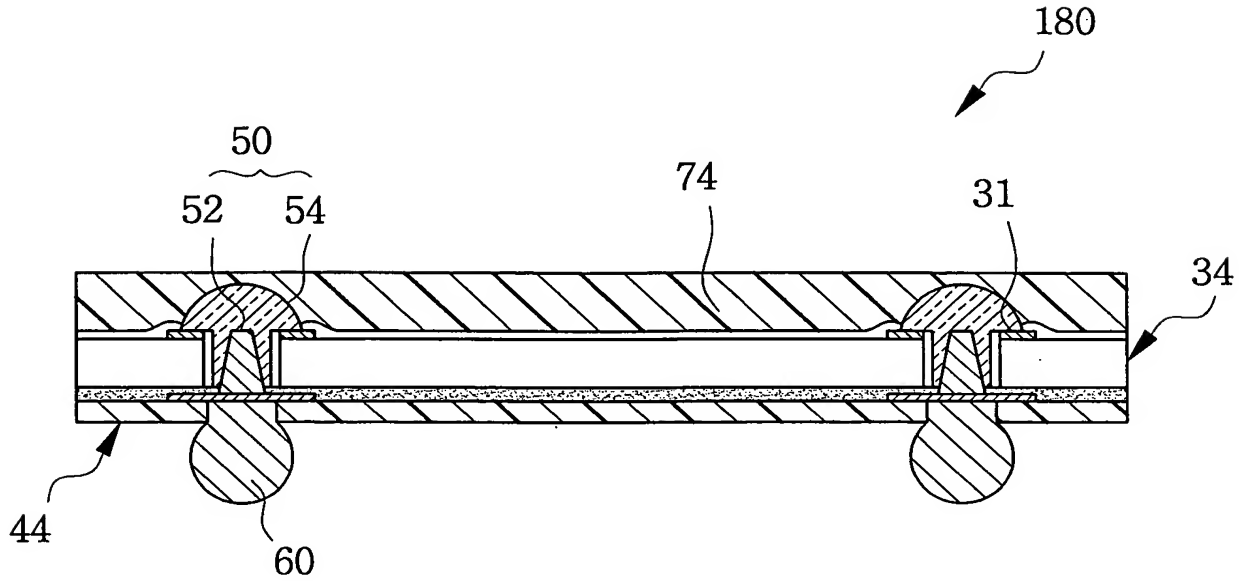
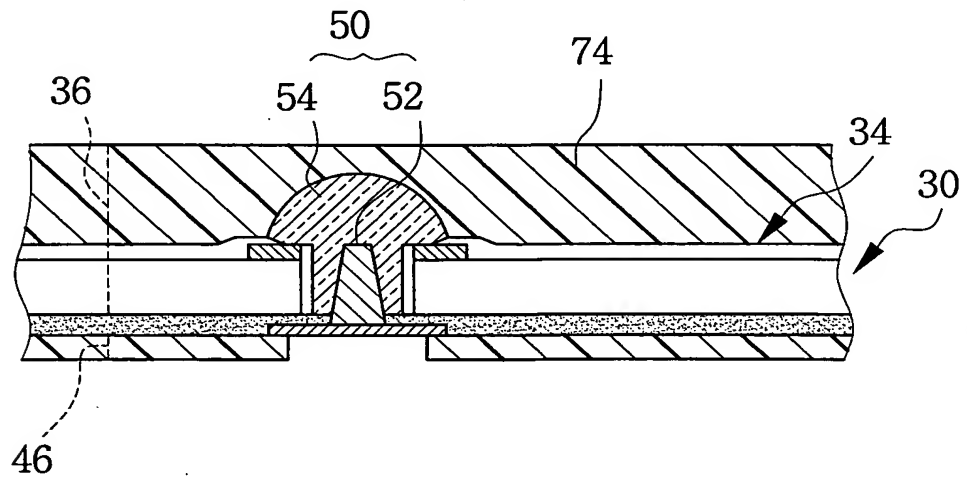


FIG .19



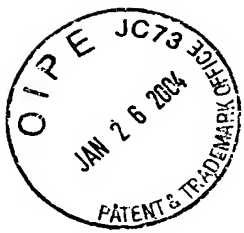


FIG .22

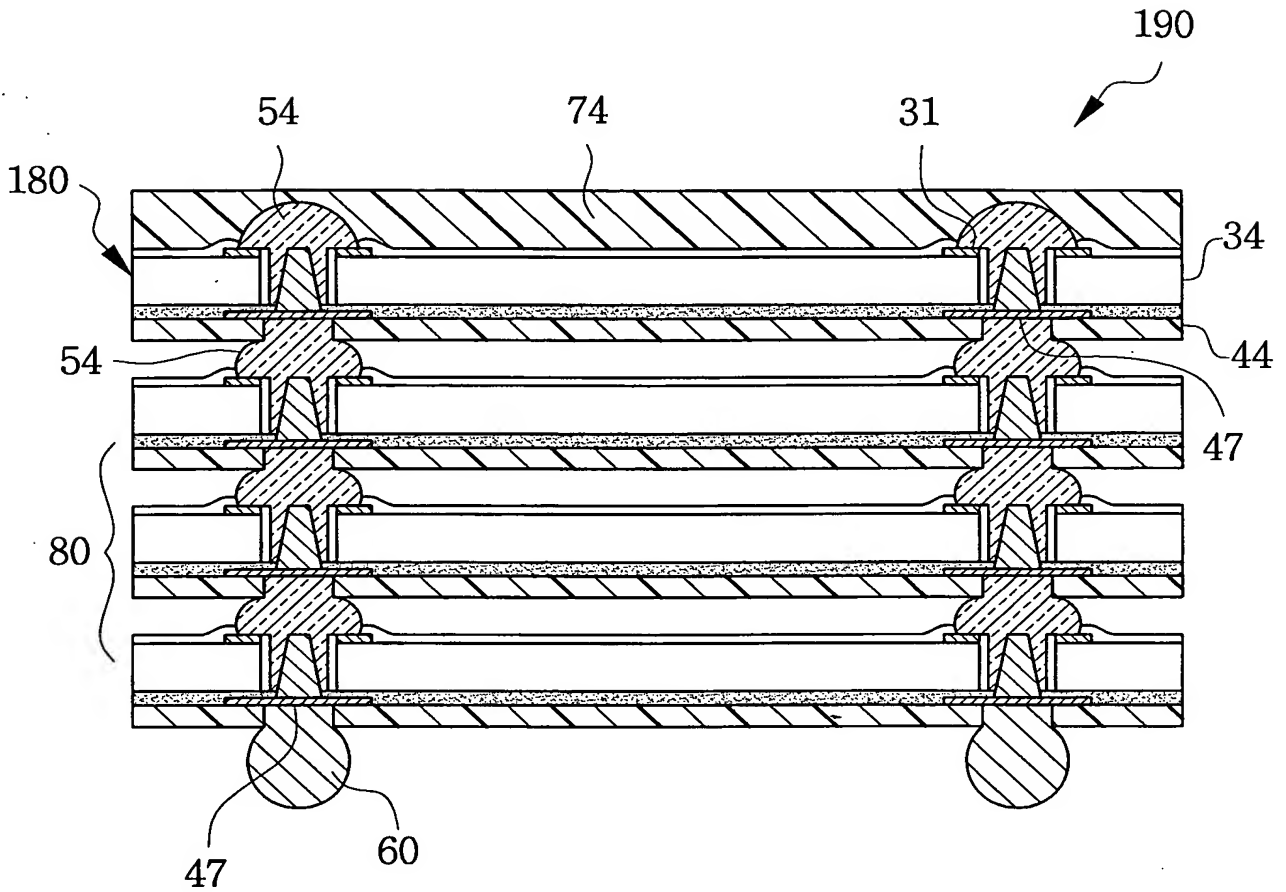
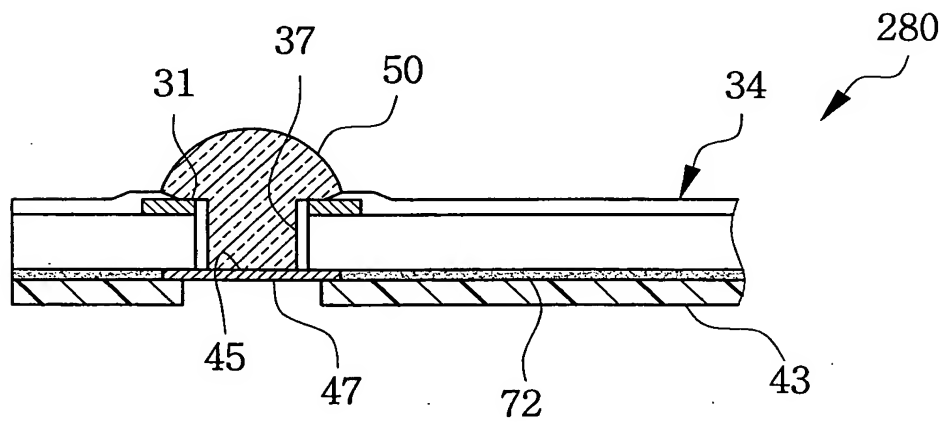


FIG .23



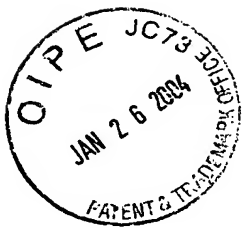


FIG .24

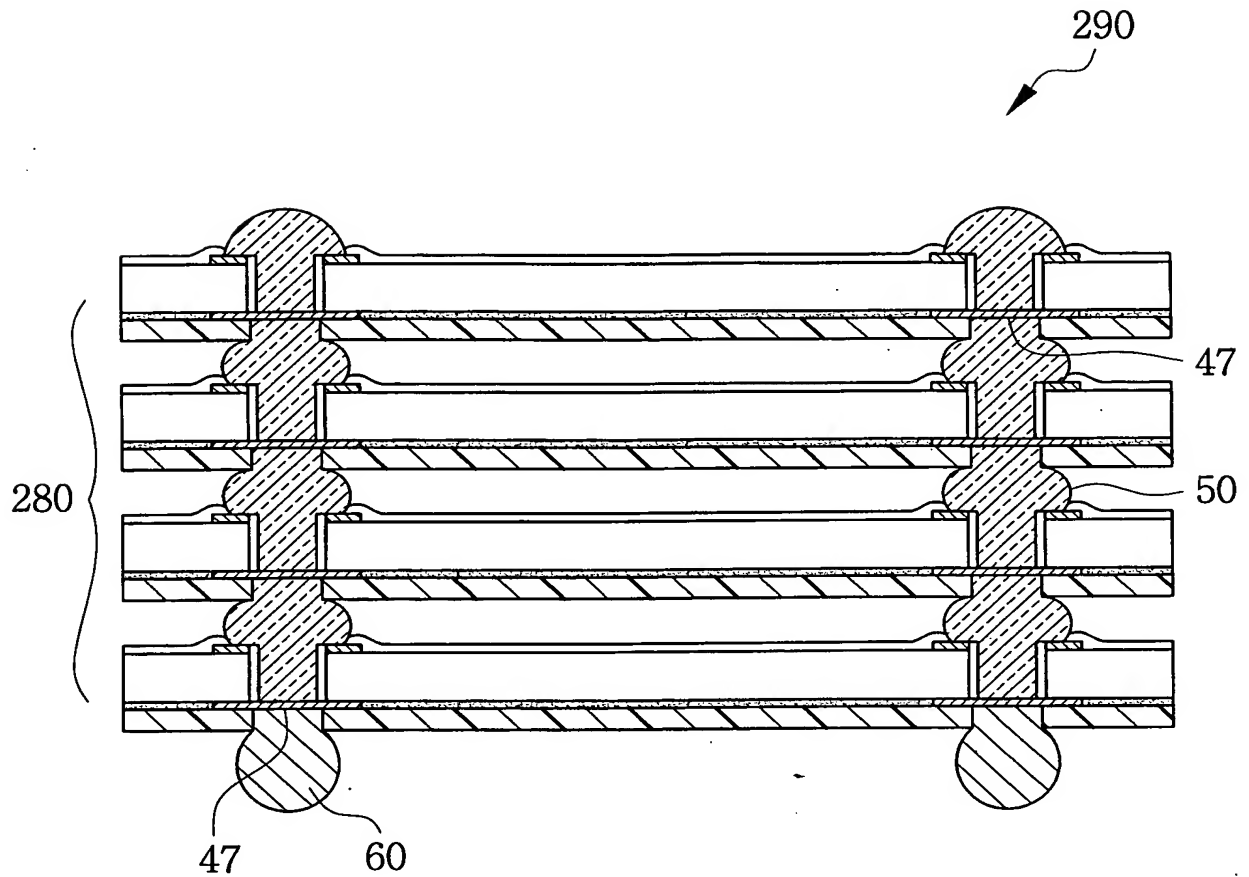
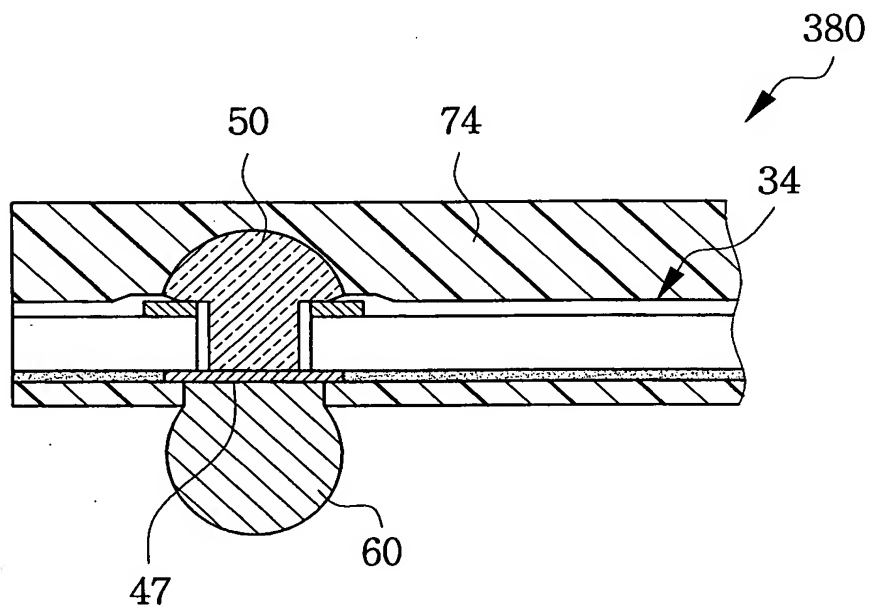


FIG .25



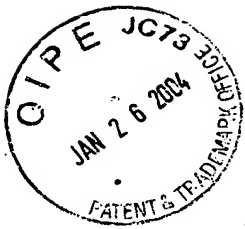


FIG .26

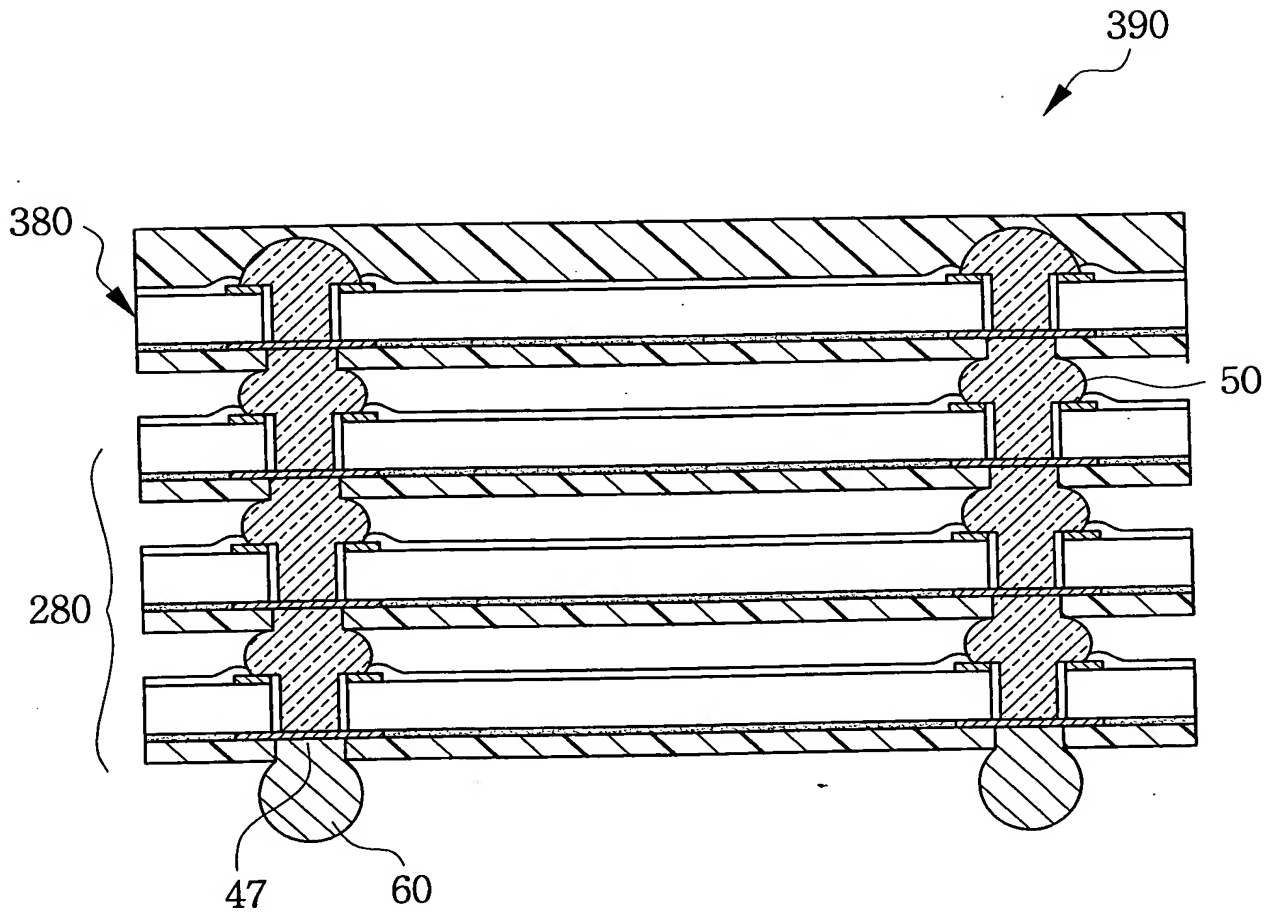
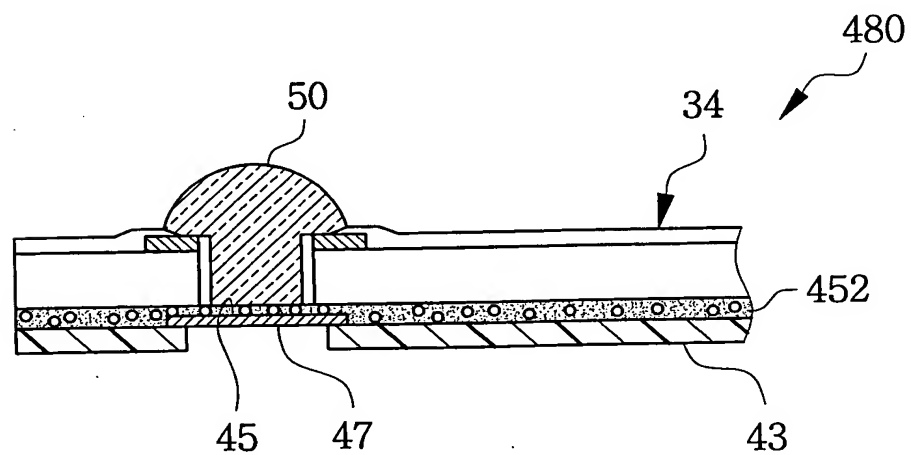


FIG .27



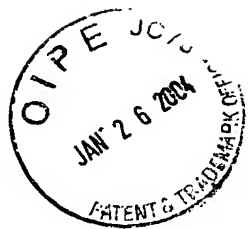


FIG .28

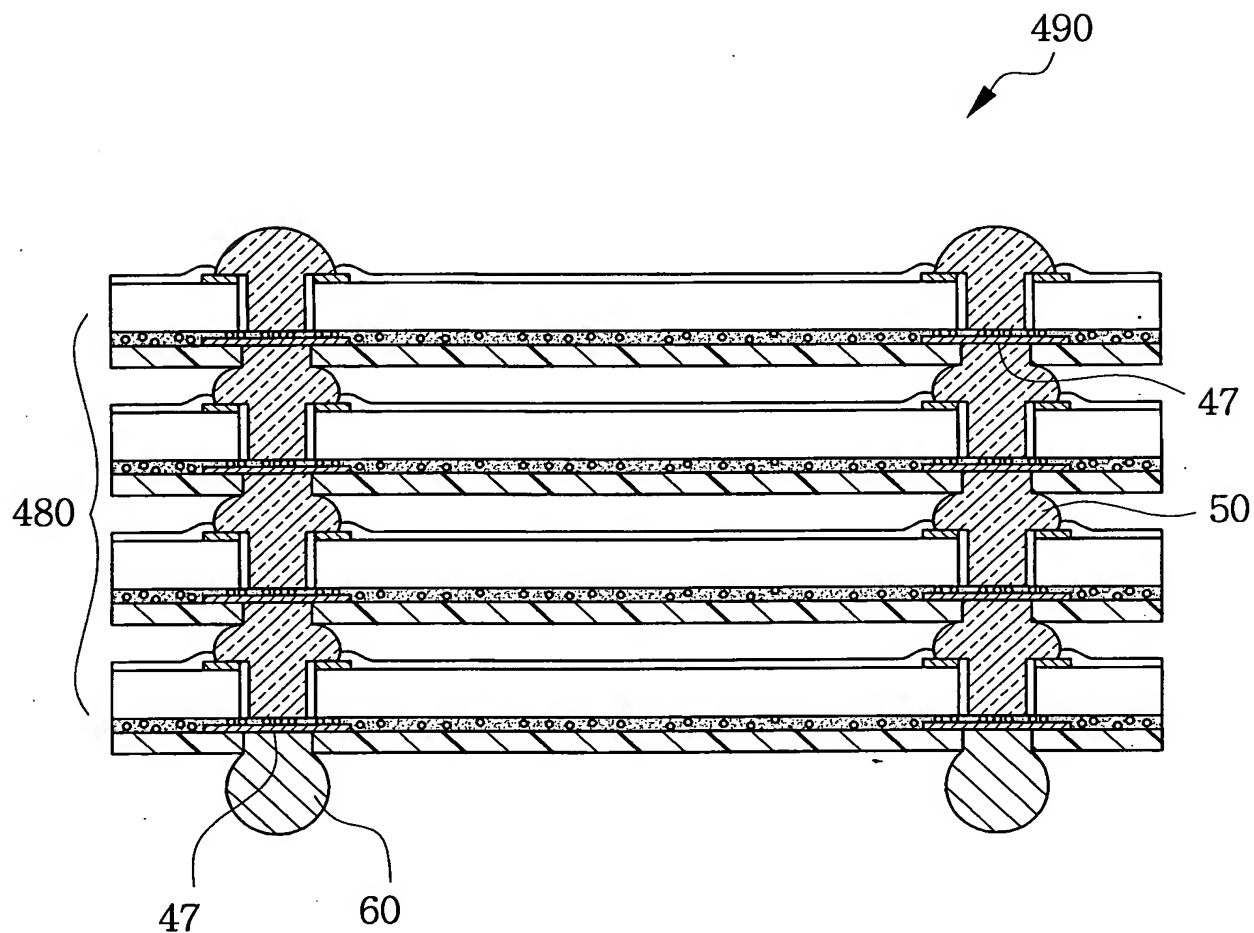
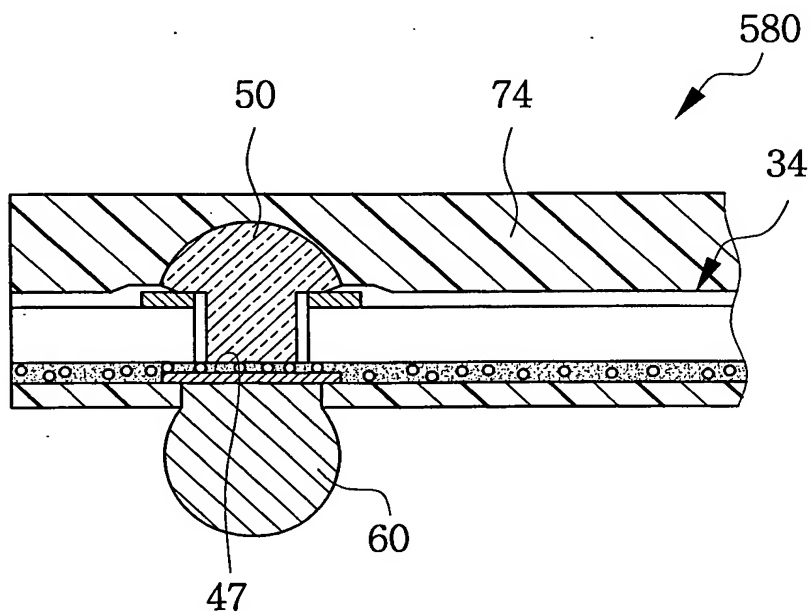


FIG .29



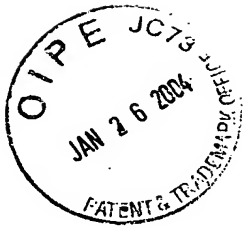
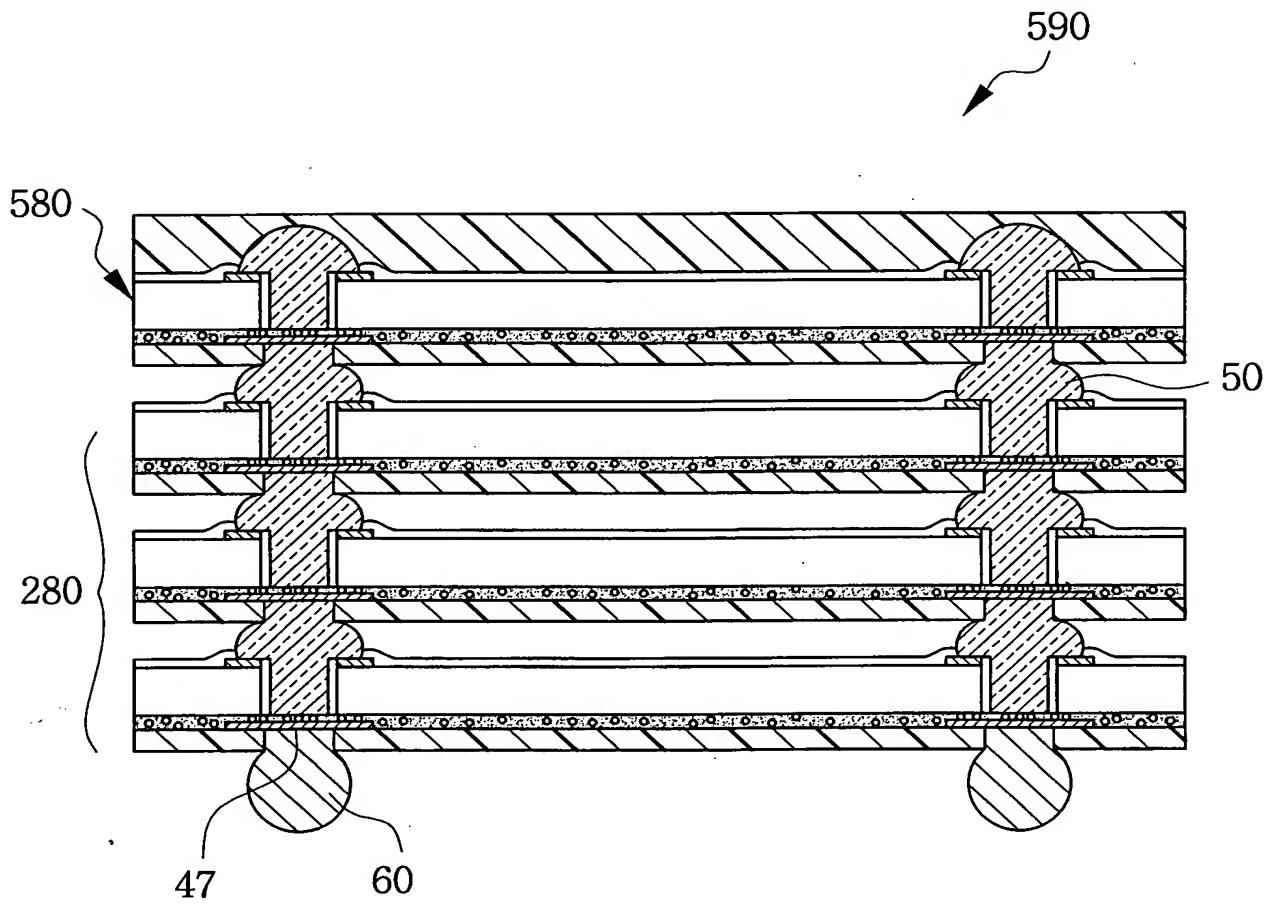


FIG .30



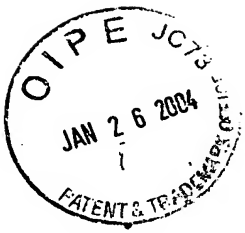


FIG .31

